

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3040216

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	TEPPEI OKAMOTO	09/25/2014
RECEIVING PARTY DATA		
Name:	RICOH IMAGING COMPANY, LTD.	
Street Address:	2-35-7 MAENO-CHO, ITABASHI-KU	
City:	TOKYO	
State/Country:	JAPAN	
Postal Code:	174-8639	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	14497786
CORRESPONDENCE DATA		
Fax Number:	(212)588-0800	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	(212) 588-0800	
Email:	mroopram@filhlaw.com	
Correspondent Name:	FROMMER LAWRENCE & HAUG	
Address Line 1:	745 FIFTH AVENUE- 10TH FL.	
Address Line 4:	NEW YORK, NEW YORK 10151	
ATTORNEY DOCKET NUMBER:	13545-2014	
NAME OF SUBMITTER:	EUGENE LEDONNE	
SIGNATURE:	/Eugene LeDonne/	
DATE SIGNED:	09/26/2014	
Total Attachments: 2		
source=01478429#page1.tif		
source=01478429#page2.tif		

DECLARATION AND ASSIGNMENT**Title of Invention: VARIABLE-MAGNIFICATION IMAGE PROCESSING APPARATUS**

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to the application attached hereto. If the application is not attached hereto, the application is as identified by the attorney docket number as set forth above and/or the following:

United States Application Number or PCT International Appln. No.

filed on

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

The undersigned hereby acknowledges that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, I, as below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in**VARIABLE-MAGNIFICATION IMAGE PROCESSING APPARATUS**

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, **RICOH IMAGING COMPANY, LTD.**, a Corporation with offices at 2-35-7 Maeno-cho, Itabashi-ku, Tokyo 174-8639, Japan (hereinafter referred to as **ASSIGNEE**) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;**NOW THEREFORE**, in exchange for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said **ASSIGNEE**, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said **ASSIGNEE**, as the assignee of the whole right, title and interest thereto;And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of **ASSIGNEE** or its designee, as **ASSIGNEE** or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the **ASSIGNEE** thereof shall hereafter require and prepare at its own expense;And I further agree that **ASSIGNEE** will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: _____, Filing Date: _____.

In witness whereof, executed on the dates indicated below.

Teppei OKAMOTO

Name of inventor

Sept. 25, 2014
Execution date of U.S. Patent Application

Tokyo, Japan

Residence of inventor

Teppei Okamoto
Signature of inventor

Sept. 25, 2014
Date of this assignment

Name of inventor

Sept. 25, 2014
Execution date of U.S. Patent Application

Residence of inventor

Teppei Okamoto
Signature of inventor

Sept. 25, 2014
Date of this assignment